

L Number	Hits	Search Text	DB	Time stamp
1	364	copper with plating with anneal\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 15:33
2	7560	anneal\$3 with remov\$3 with (top surface layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 15:34
3	19	(copper with plating with anneal\$3) same (anneal\$3 with remov\$3 with (top surface layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 16:08
4	913	438/672.ccls.	USPAT; US-PGPUB	2004/09/27 16:09
5	390	438/678.ccls.	USPAT; US-PGPUB	2004/09/27 16:08
6	1288	438/687.ccls.	USPAT; US-PGPUB	2004/09/27 16:08
7	98	257/E23.161.ccls.	USPAT; US-PGPUB	2004/09/27 16:09
8	345	438/672.ccls. and (repeat\$3 again)	USPAT; US-PGPUB	2004/09/27 16:09
9	159	438/678.ccls. and (repeat\$3 again)	USPAT; US-PGPUB	2004/09/27 16:09
10	535	438/687.ccls. and (repeat\$3 again)	USPAT; US-PGPUB	2004/09/27 16:10
11	38	257/E23.161.ccls. and (repeat\$3 again)	USPAT; US-PGPUB	2004/09/27 16:10